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Application Number	10/616,735
Filing Date	July 10, 2003
Applicant(s)	Erik Nilsen et al.
Art Unit	Unknown
Examiner Name	Unknown
Attorney Docket Number	34003.77

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

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SHEET 1 OF 1

**U. S. PATENT DOCUMENTS**

Examiner's Initials	Cite No.	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
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JH	AB	6,193,139	02/27/2001	Kivilahti
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**FOREIGN PATENT DOCUMENTS**

Examiner's Initials	Cite No.	Foreign Patent Document (Country Code - Number - Kind)	Publication Date MM-DD-YYYY	Patentee or Applicant of Cited Document	Translation YN

**OTHER PRIOR ART**

Examiner's Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article, title of the item, date, page(s), volume, issue number(s), publisher, city/country, where published
M	AD	Harsh et al., "Solder Self-Assembly for MEMS," Proceedings of the 1998 International Instrumentation Symposium (ISA'98), Reno, NV, pp. 256-261, May 3-7, 1998.
M	AE	Harsh et al., "Flip-Chip Assembly for Si-Based RF MEMS," Proceedings of the 1999 IEEE International Conference on Microelectromechanical Systems (MEMS '99), Orlando, FL, pp. 273-278, January 17-21, 1999.
M	AF	Gracias et al., "Forming Electrical Networks in Three Dimensions by Self-Assembly," Science, Volume 289, pp. 1170-1172, August 18, 2000.

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Application Number	10/616735
Filing Date	07/10/2003
Applicant(s)	Nilsen et al.
Art Unit	2812
Examiner Name	To be Determined
Attorney Docket Number	34003.77

SHEET 1 OF 4

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Examiner's Initials	Cite No.	Document Number	Publication Date MM/YYYY	Name of Patentee or Applicant of Cited Document
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**U. S. PATENT DOCUMENTS**

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**NON-PATENT LITERATURE DOCUMENTS**

Examiner's Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article, title of the item, date, page(s), volume-issue number(s), publisher, city/country where published
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M	C2	Capanu et al., "Design, Fabrication, and Testing of a Bistable Electromagnetically Actuated Microvalve", Journal of Microelectromechanical Systems, Vol. 9, No. 2, June 2000, pp. 181-188.

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SHEET	3	OF	4	Attorney Docket Number	34003.77

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Examiner Signature	<i>[Signature]</i>	Date Considered	4/11/06
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